

**WHAT IS CLAIMED IS:**

1. An electroplating apparatus, comprising:  
a first chamber containing a liquid;  
a generator that generates sonic waves; and  
a plated body disposed in liquid, wherein the sonic waves impinge on the plated body.
2. The electroplating apparatus of claim 1, further comprising a power source, wherein the plated body is coupled to a first terminal of the power source, wherein the liquid 13 is an electrically conductive liquid, and wherein a plating layer forms on the plated body according to operation of the power source.
3. The electroplating apparatus of claim 2, further comprising a plating body disposed in the liquid, wherein the plating body is coupled to a second terminal of the power source, and wherein a distance between deposited grains in the plating layer is decreased to increase at least one of density and uniformity of grain size.
4. The electroplating apparatus of claim 3, wherein the liquid is an electrolytic solution containing metal ions, wherein the power source has a positive terminal, a negative terminal, and a switch; and wherein the plating body is metal that provides ions the same as are dissolved in the electrolytic solution.



9. An electroplating device, comprising:

a wave generator that generates waves;

a chamber holding an electrolytic solution having metal ions;

a power source;

a plated body coupled to a first terminal of the power source, wherein the plated body is immersed in the electrolyte solution; and

a metal bar coupled to a second terminal of the power source, wherein the waves impinge on a surface of the plated body, and wherein the power source applies positive and negative charges to the first and second terminals, respectively.